



PRESS RELEASE:

Orbotech's SPTS Technologies' Sigma fxP PVD System Chosen by Chipmore

LCD Driver IC Packaging Services Provider Selects Industry's Most Cost Effective PVD Solution for Flip Chip Bumping Line

NEWPORT, UNITED KINGDOM, September 14, 2017 | SPTS Technologies, an Orbotech company and a supplier of advanced wafer processing solutions for the global semiconductor and related industries, today announced that it has been selected by Chipmore Technology Corporation Limited, an LCD driver integrated chip (IC) packaging specialist, to supply physical vapor deposition (PVD) solutions for the under bump metallization (UBM) and redistribution layers (RDL) for their flip-chip packaging line. Chipmore chose the Sigma[®] fxP PVD solution for their new copper (Cu) bumping line, as it provides superior results and lowest cost of ownership over competitor systems.

"Consumer demand for high-end smartphones and other mobile devices with higher resolution screens are driving the rapid growth of advanced display driver IC's," stated Mr. Kevin Crofton, Corporate Vice President at Orbotech and President of SPTS Technologies. "Our Sigma fxP PVD system provides Chipmore with the most cost effective means to expand their bumping capacity to meet the demand from display-driver IC manufacturers."

Mr. Sampus Yang, Vice President at Chipmore stated: "Chipmore offers a range of bumping solutions for our global customers, ranging from high-end gold bumping to cost-effective copper bumping for flip chip packaging. SPTS's Sigma fxP PVD system produces high quality copper pillars with excellent throughput and low cost of ownership, which allows us to remain competitive in a highly cost-sensitive market. The additional bumping capability will allow us to capitalize on consumers' growing appetite for higher resolution LCD displays and strengthen our reputation as a top packaging services company."

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About Sigma[®] fxP PVD

The Sigma fxP is a cluster PVD system used by device manufacturers in various end markets including power management, MEMS and RF devices. In semiconductor packaging, the Sigma fxP deposits RDL and under bump metals (UBM) for Cu micropillar and TSV's, plus TSV liner/barrier for 3DWLP. For FOWLP, the system carries a Multi Wafer Degas (MWD) for low temperature, high productivity degas of epoxy mold compound. Its SE-LTX etch module pre-cleans organic films with twice the mean wafers between cleans (MWBC) compared to competing systems.

About Chipmore Technology Corporation Limited

Chipmore, was established in 2004 and is headquartered in Suzhou, China, Chipmore is one of the largest display driver IC packaging and test companies in China. For display driver IC, Chipmore offers turn-key solutions, including gold bumping, wafer probing, chip-on-film (COF), and chip-on-glass (COG) packaging services. For Non-display driver IC (Power IC Switch, RF) Chipmore offers Cu pillar bumping, CuNiAu bumping and wafer probing. Chipmore is wholly owned by Chipbond. For more information, visit www.chipmore.com.cn

About Orbotech Ltd.

Orbotech Ltd. is a leading global supplier of yield-enhancing and process-enabling solutions for the manufacture of electronics products. Orbotech provides cutting-edge solutions for use in the manufacture of printed circuit boards (PCBs), flat panel displays (FPDs), and semiconductor devices (SDs), designed to enable the production of innovative, next-generation electronic products and improve the cost effectiveness of existing and future electronics production processes. Orbotech's core business lies in enabling electronic device manufacturers to inspect and understand PCBs and FPDs and to verify their quality ('reading'); pattern the desired electronic circuitry on the relevant substrate and perform three-dimensional shaping of metalized circuits on multiple surfaces ('writing'); and utilize advanced vacuum deposition and etching processes in SD and semiconductor manufacturing ('connecting'). Orbotech refers to this 'reading', 'writing' and 'connecting' as enabling the 'Language of Electronics'. For more information, visit www.orbotech.com and www.spts.com.

About SPTS Technologies

SPTS Technologies, an Orbotech company, designs, manufactures, sells, and supports etch, PVD, and CVD wafer processing solutions for the MEMS, advanced packaging, LED, high speed RF on GaAs, and power management device markets. With manufacturing facilities in Newport, Wales, and Allentown, Pennsylvania, the company operates across 19 countries in Europe, North America and Asia-Pacific. For more information about SPTS Technologies, please visit www.spts.com

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